DATA SHEET

BYW29EX series
Rectifier diodes
ultrafast, rugged

Product specification

October 1998

Rectifier diodes ultrafast, rugged

BYW29EX series

GENERAL DESCRIPTION

Glass passivated epitaxial rectifier diodes in a full pack plastic envelope, featuring low forward voltage drop, ultra-fast recovery times, soft recovery characteristic and guaranteed reverse surge and ESD capability. They are intended for use in switched mode power supplies and high frequency circuits in general where low conduction and switching losses are essential.

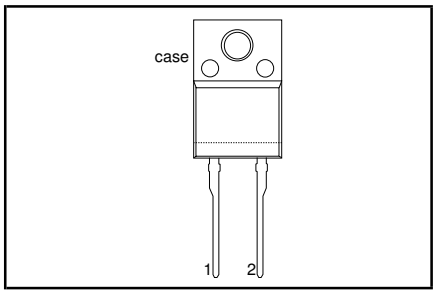
QUICK REFERENCE DATA

SYMBOL	PARAMETER	MAX.	MAX.	UNIT
	BYW29EX-	**150**	**200**	
V_{RRM}	Repetitive peak reverse voltage	150	200	V
V_F	Forward voltage	0.895	0.895	V
$I_{F(AV)}$	Forward current	8	8	A
t_{rr}	Reverse recovery time	25	25	ns
I_{RRM}	Repetitive peak reverse current	0.2	0.2	A

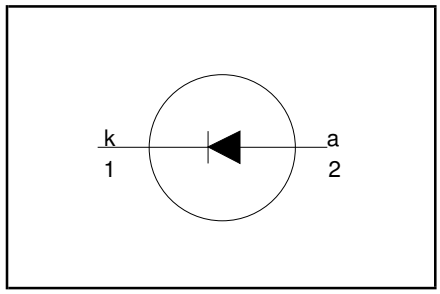
PINNING - SOD113

PIN	DESCRIPTION
1	cathode
2	anode
case	isolated

PIN CONFIGURATION



SYMBOL



LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.		UNIT
				-150	**-200**	
V_{RRM}	Repetitive peak reverse voltage		-	150	200	V
V_{RWM}	Crest working reverse voltage		-	150	200	V
V_R	Continuous reverse voltage		-	150	200	V
$I_{F(AV)}$	Average forward current[1]	square wave; $\delta = 0.5$; $T_{hs} \leq 106$ ˚C	-	8		A
		sinusoidal; a = 1.57; $T_{hs} \leq 109$ ˚C	-	7.3		A
$I_{F(RMS)}$	RMS forward current		-	11.3		A
I_{FRM}	Repetitive peak forward current	t = 25 µs; $\delta = 0.5$; $T_{hs} \leq 106$ ˚C	-	16		A
I_{FSM}	Non-repetitive peak forward current	t = 10 ms	-	80		A
		t = 8.3 ms	-	88		A
		sinusoidal; with reapplied $V_{RWM(max)}$				
I^2t	I^2t for fusing	t = 10 ms	-	32		A^2s
I_{RRM}	Repetitive peak reverse current	$t_p = 2$ µs; $\delta = 0.001$	-	0.2		A
I_{RSM}	Non-repetitive peak reverse current	$t_p = 100$ µs	-	0.2		A
T_{stg}	Storage temperature		-40	150		˚C
T_j	Operating junction temperature		-	150		˚C

1 Neglecting switching and reverse current losses

ESD LIMITING VALUE

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_C	Electrostatic discharge capacitor voltage	Human body model; C = 250 pF; R = 1.5 kΩ	-	8	kV

ISOLATION LIMITING VALUE & CHARACTERISTIC

T_{hs} = 25 ˚C unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V_{isol}	R.M.S. isolation voltage from both terminals to external heatsink	f = 50-60 Hz; sinusoidal waveform; R.H. ≤ 65% ; clean and dustfree	-		2500	V
C_{isol}	Capacitance from both terminals to external heatsink	f = 1 MHz	-	10	-	pF

THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$R_{th\ j\text{-}hs}$	Thermal resistance junction to heatsink	with heatsink compound	-	-	5.5	K/W
		without heatsink compound	-	-	7.2	K/W
$R_{th\ j\text{-}a}$	Thermal resistance junction to ambient	in free air	-	55	-	K/W

STATIC CHARACTERISTICS

T_j = 25 ˚C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V_F	Forward voltage	I_F = 8 A; T_j = 150˚C	-	0.80	0.895	V
		I_F = 8 A	-	0.92	1.05	V
		I_F = 20 A	-	1.1	1.3	V
I_R	Reverse current	$V_R = V_{RWM}$; T_j = 100 ˚C	-	0.2	0.6	mA
		$V_R = V_{RWM}$	-	2	10	µA

DYNAMIC CHARACTERISTICS

T_j = 25 ˚C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Q_s	Reverse recovery charge	I_F = 2 A; $V_R \geq$ 30 V; $-dI_F/dt$ = 20 A/µs	-	4	11	nC
t_{rr1}	Reverse recovery time	I_F = 1 A; $V_R \geq$ 30 V; $-dI_F/dt$ = 100 A/µs	-	20	25	ns
t_{rr2}	Reverse recovery time	I_F = 0.5 A to I_R = 1 A; I_{rec} = 0.25 A	-	15	20	ns
V_{fr}	Forward recovery voltage	I_F = 1 A; dI_F/dt = 10 A/µs	-	1	-	V

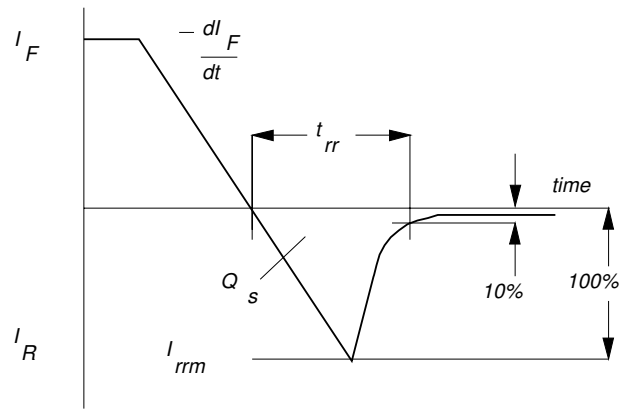


Fig.1. Definition of t_{rr1}, Q_s and I_{rrm}

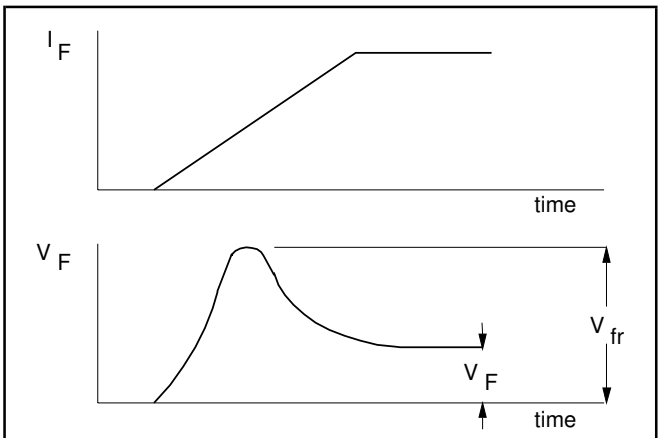


Fig.2. Definition of V_{fr}

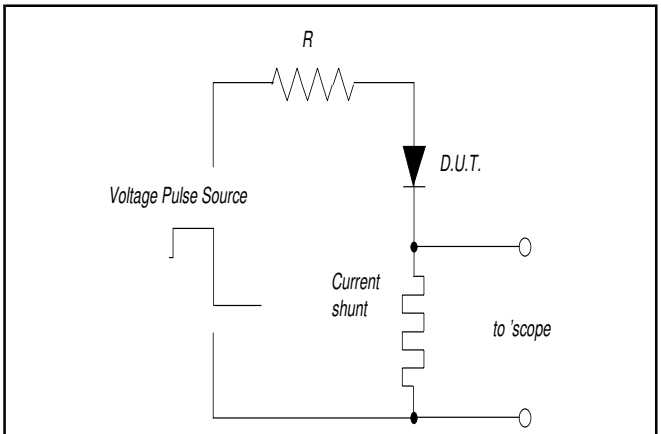


Fig.3. Circuit schematic for t_{rr2}

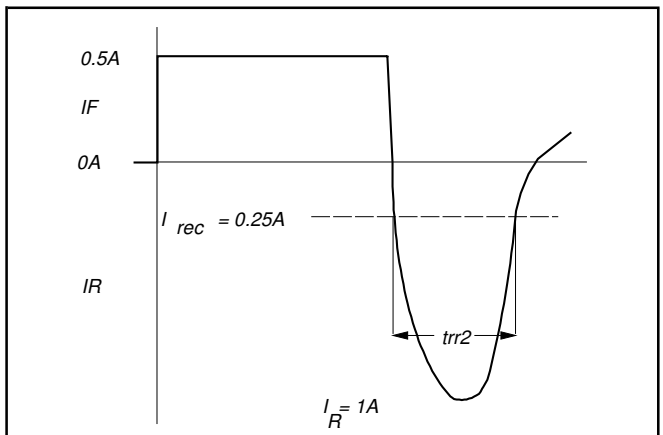


Fig.4. Definition of t_{rr2}

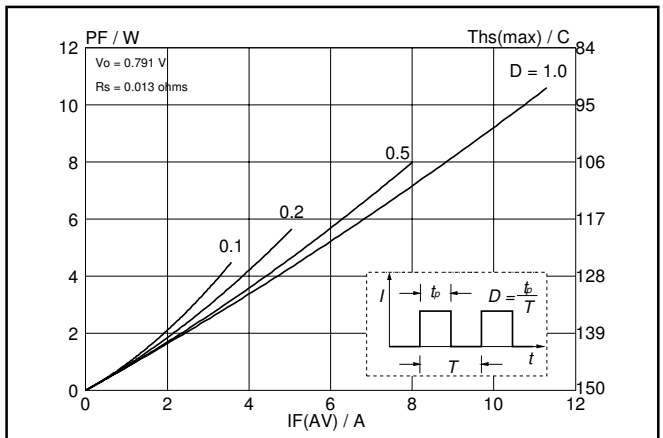


Fig.5. Maximum forward dissipation $P_F = f(I_{F(AV)})$; square current waveform where $I_{F(AV)} = I_{F(RMS)} \times \sqrt{D}$.

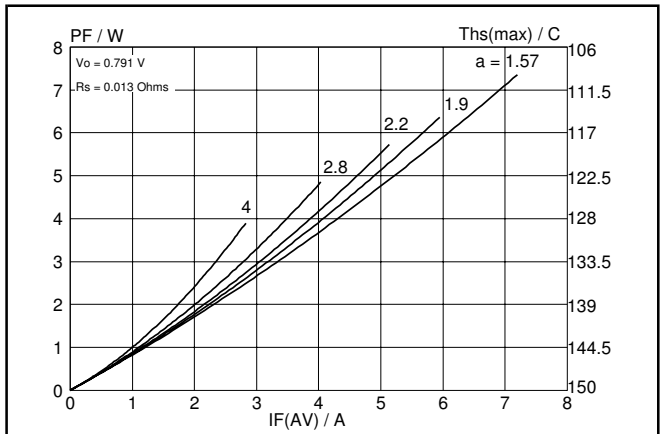


Fig.6. Maximum forward dissipation $P_F = f(I_{F(AV)})$; sinusoidal current waveform where a = form factor = $I_{F(RMS)} / I_{F(AV)}$.

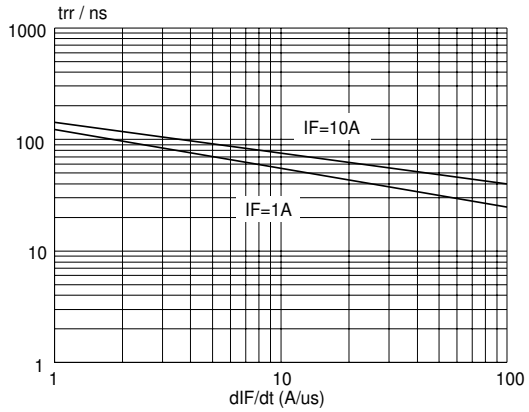


Fig.7. Maximum t_{rr} at T_j = 25 ˚C.

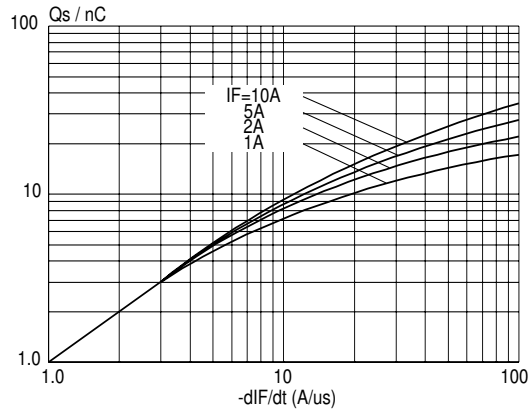


Fig.10. Maximum Q_s at T_j = 25 ˚C.

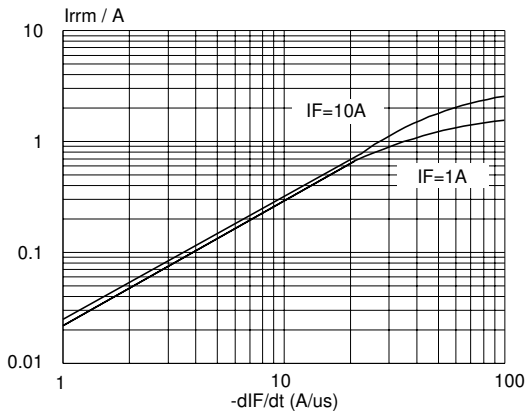


Fig.8. Maximum I_{rrm} at T_j = 25 ˚C.

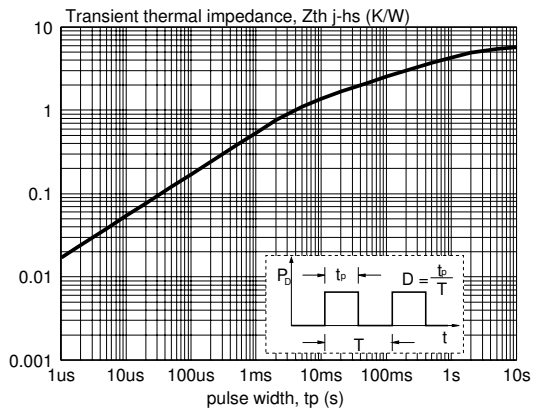


Fig.11. Transient thermal impedance; $Z_{th\ j\text{-}hs} = f(t_p)$.

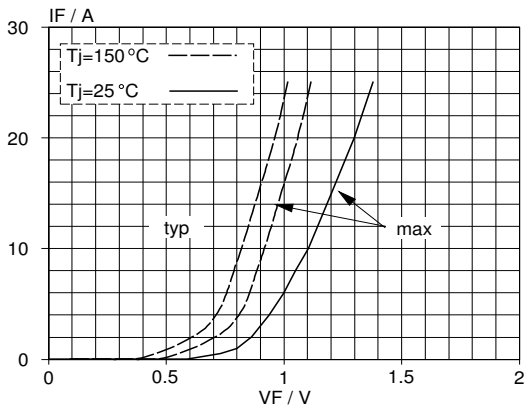


Fig.9. Typical and maximum forward characteristic $I_F = f(V_F)$; parameter T_j

MECHANICAL DATA

Dimensions in mm

Net Mass: 2 g

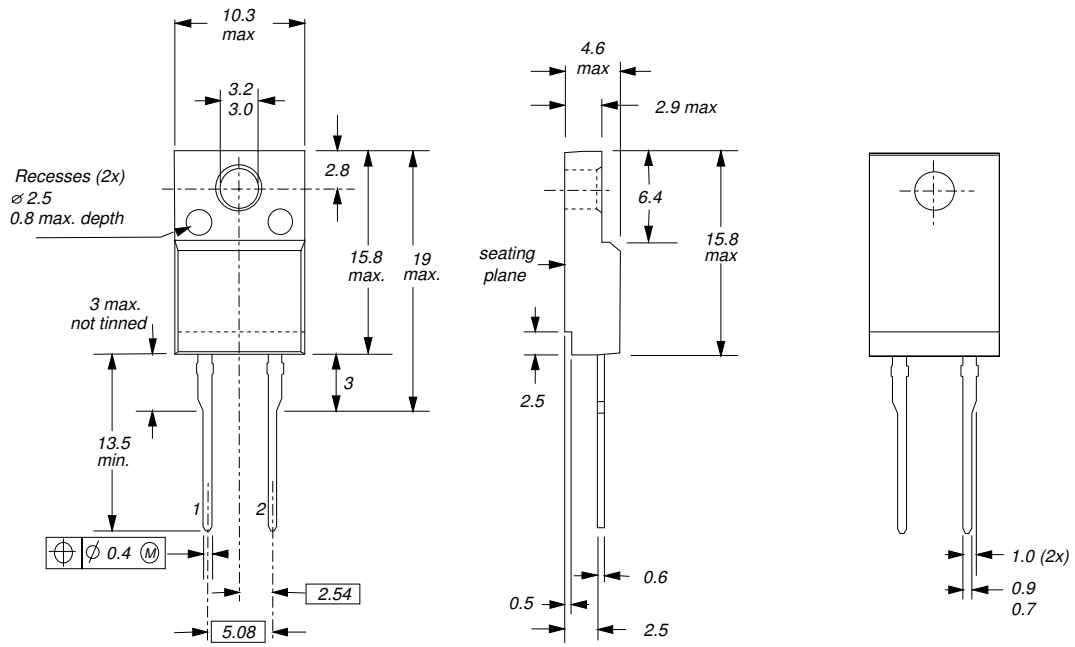


Fig.12. SOD113; The seating plane is electrically isolated from all terminals.

Notes
1. Refer to mounting instructions for F-pack envelopes.
2. Epoxy meets UL94 V0 at 1/8".

Legal information

DATA SHEET STATUS

DOCUMENT STATUS[1]	PRODUCT STATUS[2]	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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